PRESS RELEASE

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Press Contact: Michael L. Martel, MMC, Inc.
Tel. 401-480-3433;
Email: mmcmarketing@gmail.com

Booth #3300

TopLine Corporation to Exhibit Packages, Learning Solutions at APEX Expo

Anaheim, California, USA – TopLine Corporation will exhibit a number of innovative solutions and learning tools at APEX Expo 2026, in Booth# 3300.

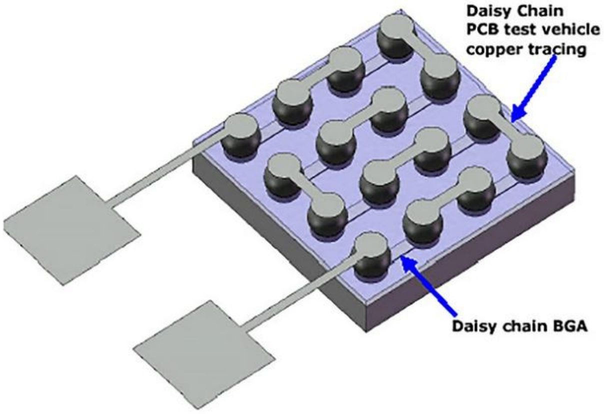
The main features on display will be as follows:

1. CCGAs and CCGA Tooling for Column Attach;

2. Large Dimension BGA - Up to 100mm;

3. Tanaka Bonding Wire.

4. Trays - JEDEC Matrix and Waffle Pack IC Trays.



For SMT process development, TopLine will display Large Daisy Chain BGA packages, 70mm to 100mm in size; also displayed will be:

1. SOT Jumpers.

2. Solderable Spacers; and

3. A plethora of test components from ceramic CLCC to discrete chips.

For more information, Tel. 1-800-776-9888, email info@TopLine.tv, or visit www.TopLine.tv.

About TopLine

TopLine manufactures a wide range of solder columns for CCGA semiconductor packages, and provides Daisy Chain CCGA packages for engineering development, profiling and practice. TopLine products provide hands-on learning for engineers. TopLine is a pioneer in CGA solder columns technology and low temperature cryogenic package-to-board interconnects. To learn more, visit www.TopLine.tv or call (1+) 800 – 776-9888.

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